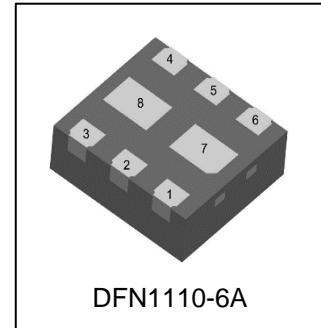


LSI1012X6T3BG

S-LSI1012X6T3BG

20 V, Dual N-channel Trench MOSFET

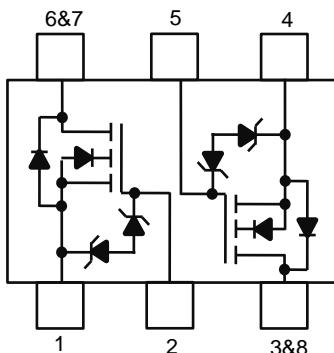


1. FEATURES

- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.
- Trench MOSFET technology

2. APPLICATION

- Relay driver
- High-speed line driver
- Low-side load switch
- Switching circuits



3. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
LSI1012X6T3BG	A1	5000/Tape&Reel

4. MAXIMUM RATINGS($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	VDSS	20	V
Gate-Source Voltage	VGSS	± 8	V
Drain Current ($T_A = 25^\circ\text{C}$, $V_{GS} = 4.5\text{ V}$) ($T_A = 100^\circ\text{C}$, $V_{GS} = 4.5\text{ V}$)	ID	0.6 0.4	A
Pulsed Drain Current ($T_A = 25^\circ\text{C}$, single pulse, $t_p \leq 10\text{ }\mu\text{s}$)	IDM	2.5	A
Storage Temperature	Tstg	-55~+150	°C
Junction Temperature	TJ	150	°C

5. THERMAL CHARACTERISTICS

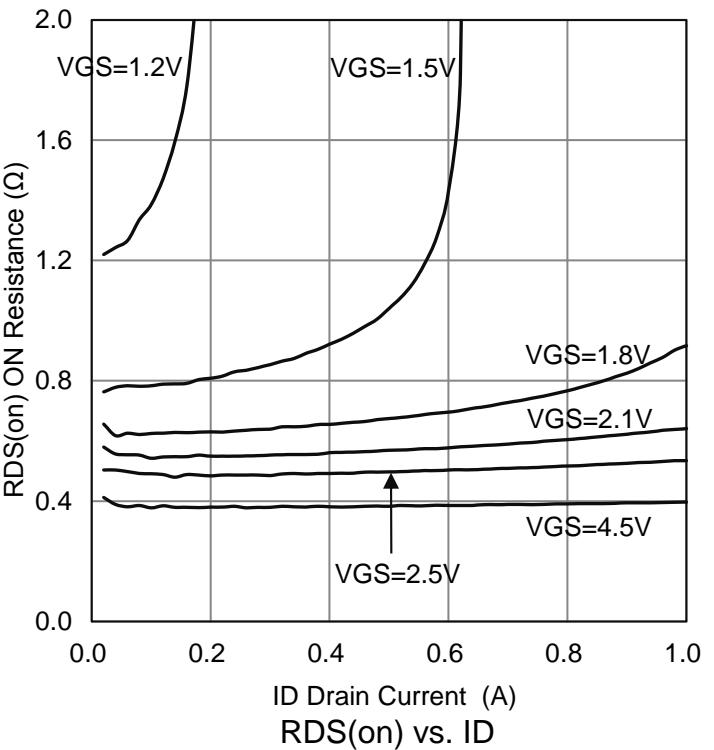
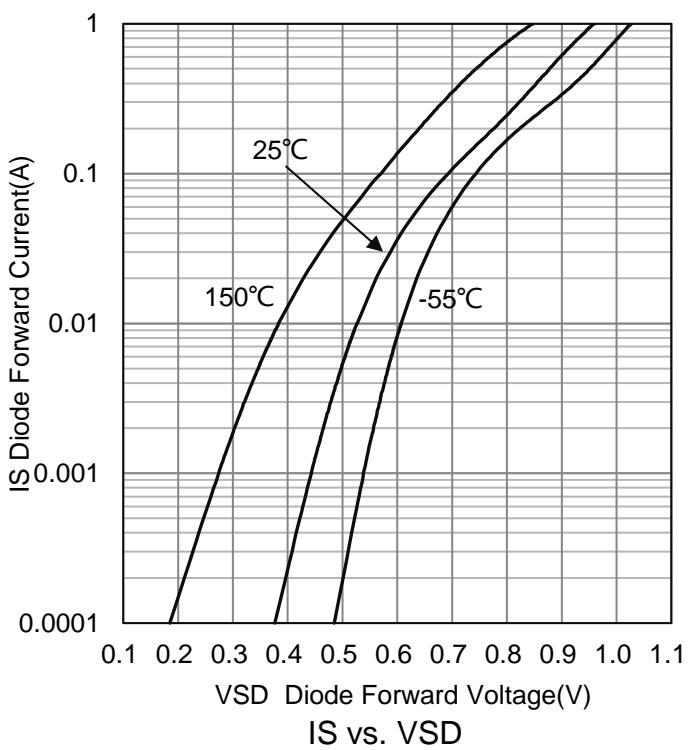
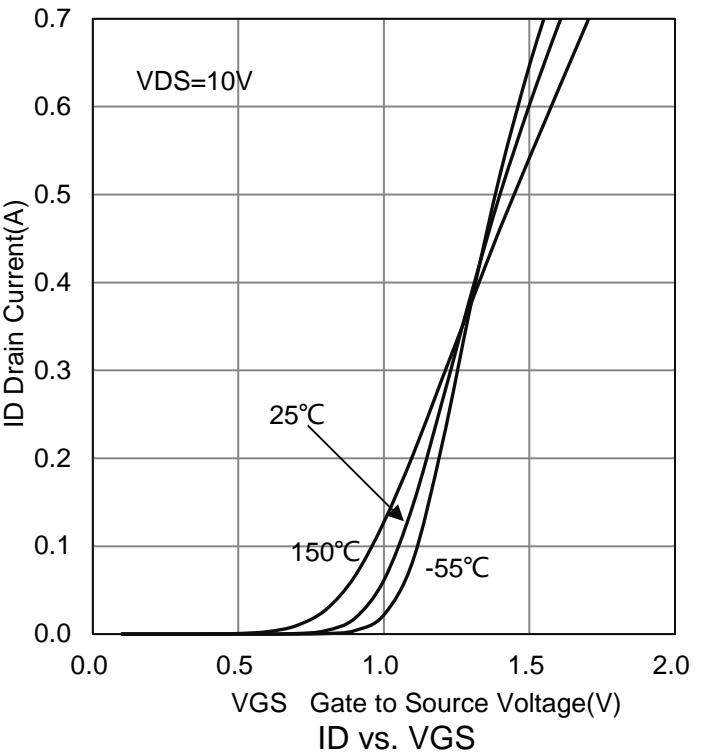
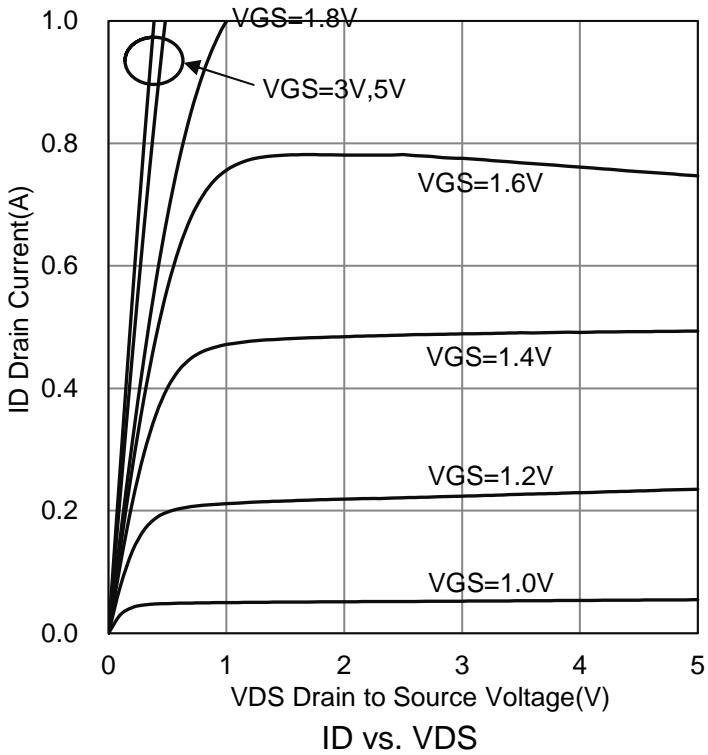
Parameter	Symbol	Limits	Unit
Maximum Power Dissipation	PD	250	mW
Thermal Resistance, Junction-to-Ambient(Note 1)	R _{θJA}	500	°C/W
Junction-to-Case	R _{θJC}	300	°C/W

1. 30.0mm×25.0mm×1.6mm(FR4).

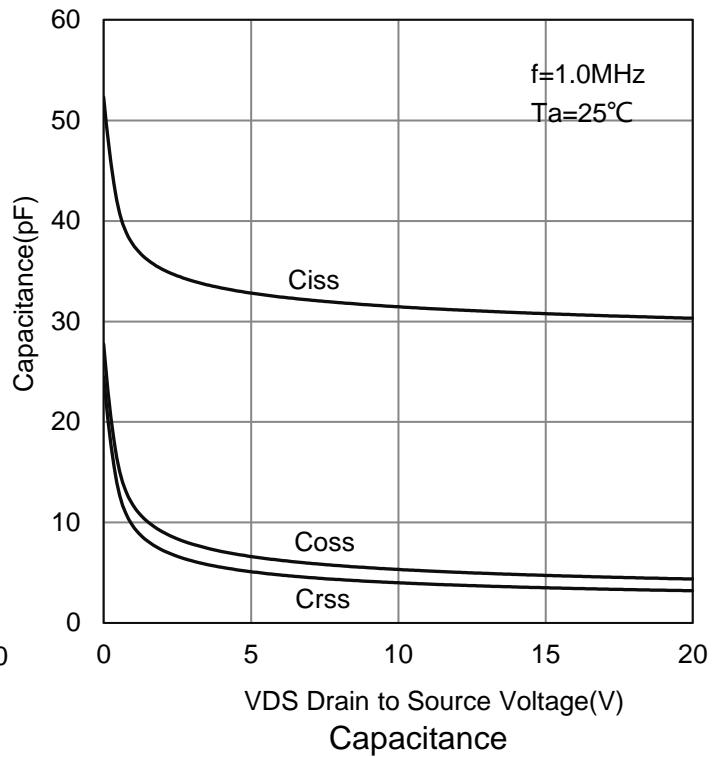
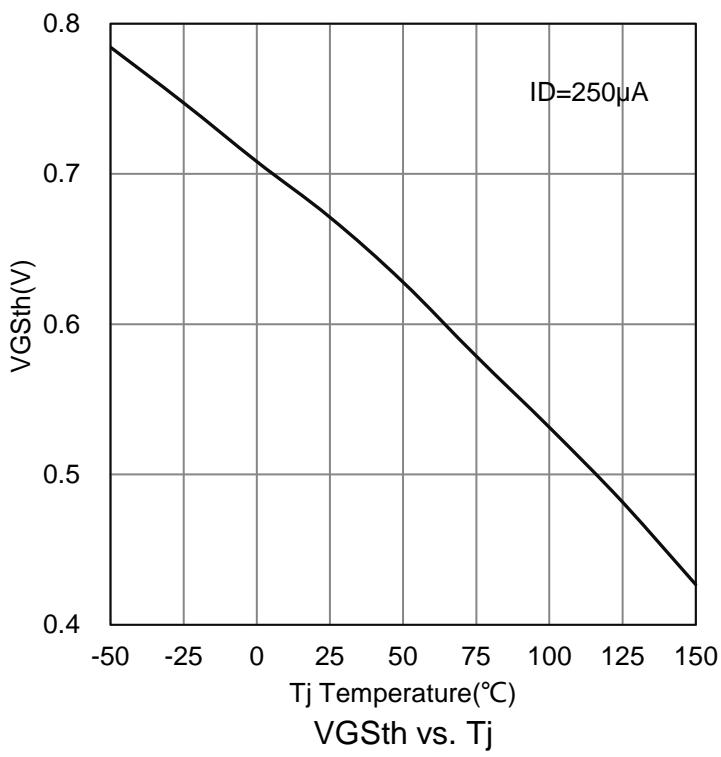
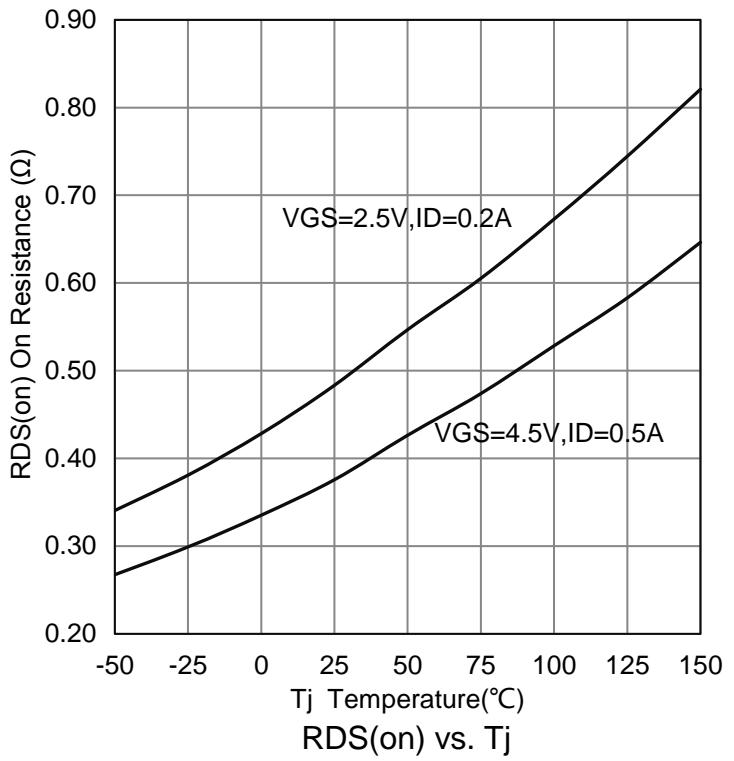
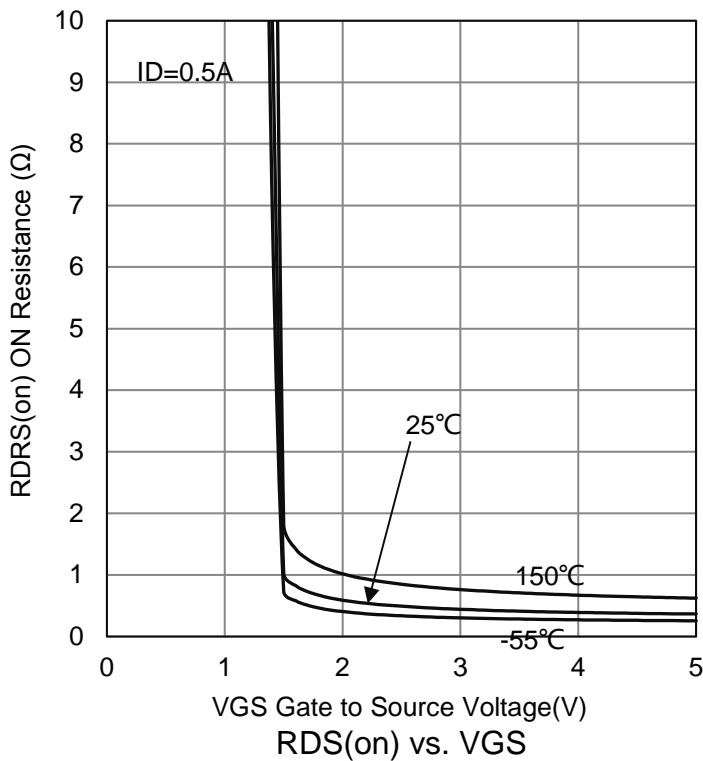
6. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Static					
Drain-Source Breakdown Voltage (VGS = 0 V, IDS = 250 µA)	BVDSS	20	-	-	V
Gate Threshold Voltage (VDS = VGS , IDS = 250 µA)	VGS(th)	0.4	0.65	1	V
Drain Leakage Current (VDS = 16 V, VGS = 0V)	IDSS	-	-	1	µA
Gate Leakage Current (VGS = ±8 V, VDS = 0 V)	IGSS	-	-	±10	µA
Drain-Source On-State Resistance (VGS = 4.5 V, IDS = 0.5 A) (VGS = 2.5 V, IDS = 0.2 A) (VGS = 1.8 V, IDS = 0.1 A) (VGS = 1.5 V, IDS = 0.05 A) (VGS = 1.2 V, IDS = 0.02 A)	RDS(ON)	- - - - -	0.45 0.55 0.75 1.2 2.5	0.6 0.8 1.2 - -	Ω
Diode Forward Voltage (IS = 0.5 A, VGS = 0 V)	VSD	-	0.8	1.3	V
Dynamic					
Input Capacitance	(VGS = 0 V, VDS = 10 V,f=1MHz)	Ciss	-	31	-
Output Capacitance		Coss	-	5.36	-
Reverse Transfer Capacitance		Crss	-	4	-
Total Gate Charge	(VGS = 4.5 V, VDS = 10 V, ID = 0.6 A)	Qg	-	0.51	-
Gate-Source Charge		Qgs	-	0.05	-
Gate-Drain Charge		Qgd	-	0.20	-
Gate Resistance (VDS=0V ,VGS=0V, f=1.0MHz)	Rg	-	83	-	Ω

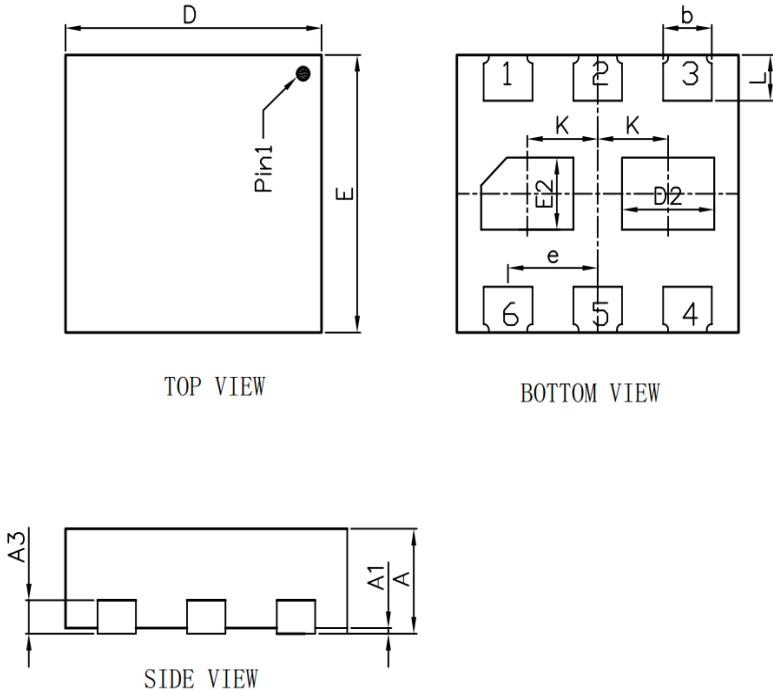
7.ELECTRICAL CHARACTERISTICS CURVES



7.ELECTRICAL CHARACTERISTICS CURVES(Con.)



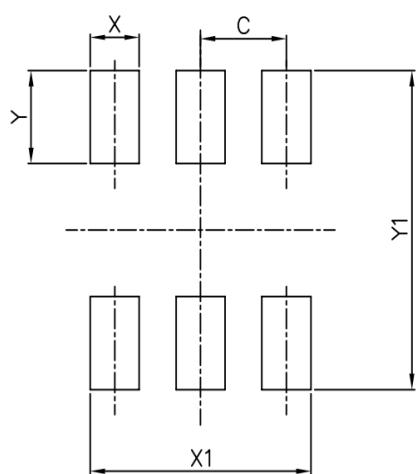
8.OUTLINE AND DIMENSIONS



DFN1110-6A			
DIM	Min.	Typ.	Max.
A	0.34	0.37	0.40
A1	0.01	0.02	0.04
b	0.15	0.19	0.23
L	0.125	0.165	0.205
D	1.05	1.10	1.15
E	0.95	1.00	1.05
D2	0.32	0.36	0.40
E2	0.22	0.26	0.30
e	0.35		
A3	0.127 Ref.		
K	0.275		

All Dimensions in mm

9.SOLDERING FOOTPRINT



DFN1110-6A	
Dim	(mm)
X	0.20
Y	0.35
C	0.35
X1	0.90
Y1	1.20



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